

Î HAY 'Hcd '%\$\$'; `cVU` 'HY WA bc`c[m' Leaders are the organizations poised hc 'dfcdY` 'h\Y' Z hi fY 'c ZhY WA bc`c[m' , Brian Scanlon, Ch.hf,

The ONLY Back-end Equipment Supplier Being Recognized

ASM Pacific Technology © 2018 page 3





ASMPT Global Presence

ASM Pacific Technology © 2018

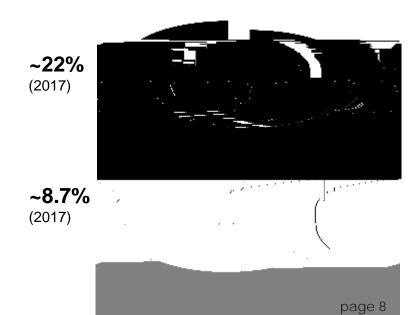




Three Business Segments With Leading Market Positions

Worldwide Market Position & Share

~25% (2017)









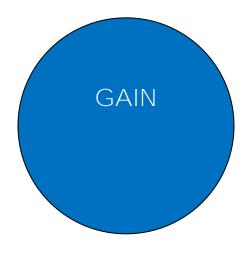
Q1 2018 Segments Highlights







Key Strategies for Sustainable Growth & Profitability



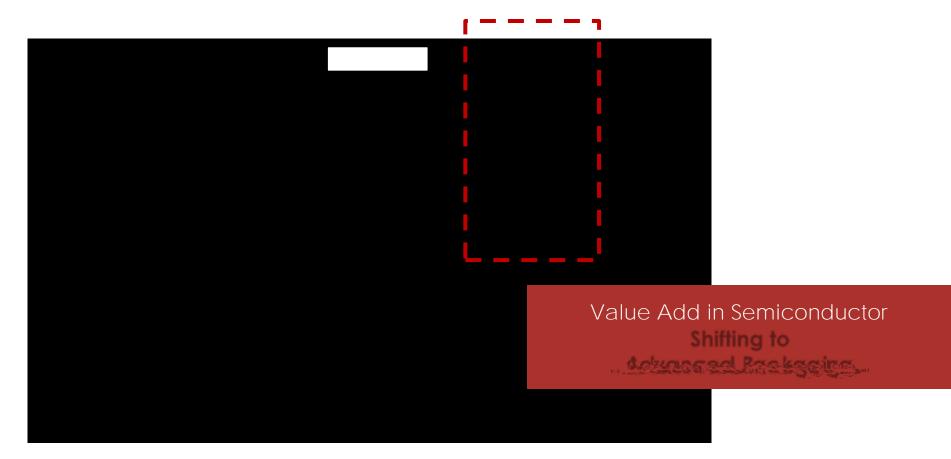
ASM Pacific Technology © page 18



5G will be the Data Highway



Advanced Packaging is a High Growth Area



ASM Pacific Technology © 2018





New Target Market for ASMPT -- Memory

Wire Bonding System (NAND)

LASER Grooving I[W)-2(ire)-9(Bon)4(din)4(g)-12(Sy)20(stem)3()-37W0 0 (369.5ty)2h TJ(E





Industry Growth Forecast (2017-2018)

Ī					
-					
-					
-					
_	2212			1	
	2013	2014	2015		





Outlook

Expect Q2 Group Billings to be in the range of US\$650m to US\$710m

Supported by the strong backlog

Anticipate Q2 Bookings to achieve a single digit percent YoY growth

Following very strong bookings in Q1

Expect Q2 Group GM to improve over Q1, supported by the expected high turnover

Strong Q1 booking momentum reaffirmed our belief that the semiconductor industry

has entered into a different phase and driven by multiple growth drivers such as

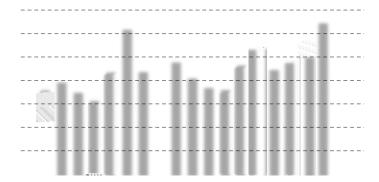
IoT, industry automation, robotics, smart factory, power management, automotive, smart city, cloud computing, data center, AI, big data analysis, and smartphone

Together with 5G mobile network, these diversified applications will spur up demand for semiconductors devices and our products





Q1 2018 Quarterly Billings







Recent Awards & Recognition

Technology Achievement Grand Award of HKIA 2017

(for the third time)

Federation of HK Industries

